

ACADEMIC REGULATIONS COURSE STRUCTURE AND DETAILED SYLLABUS

**For
M.Tech. MECHANICAL BRANCH**

Specialization :

CAD/CAM



**JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY KAKINADA
KAKINADA - 533 003, Andhra Pradesh, India**

ACADEMIC REGULATIONS R13 FOR M. Tech (REGULAR)
DEGREE COURSE

Applicable for the students of M. Tech (Regular) Course from the Academic Year 2013-14 onwards

The M. Tech Degree of Jawaharlal Nehru Technological University Kakinada shall be conferred on candidates who are admitted to the program and who fulfil all the requirements for the award of the Degree.

1.0 ELIGIBILITY FOR ADMISSIONS

Admission to the above program shall be made subject to eligibility, qualification and specialization as prescribed by the University from time to time.

Admissions shall be made on the basis of merit/rank obtained by the candidates at the qualifying Entrance Test conducted by the University or on the basis of any other order of merit as approved by the University, subject to reservations as laid down by the Govt. from time to time.

2.0 AWARD OF M. Tech DEGREE

- 2.1 A student shall be declared eligible for the award of the M. Tech Degree, if he pursues a course of study in not less than two and not more than four academic years.
- 2.2 The student shall register for all 80 credits and secure all the 80 credits.
- 2.3 The minimum instruction days in each semester are 90.

3.0 A. COURSES OF STUDY

The following specializations are offered at present for the M. Tech course of study.

1. M.Tech- Structural Engineering
2. M.Tech- Transportation Engineering
3. M.Tech- Infrastructure Engineering & Management
4. ME- Soil Mechanics and Foundation Engineering
5. M.Tech- Environmental Engineering
6. M.Tech-Geo-Informatics
7. M.Tech-Spatial Information Technology

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8. M.Tech- Civil Engineering
 9. M.Tech -Geo-Technical Engineering
 10. M.Tech- Remote Sensing
 11. M.Tech- Power Electronics
 12. M.Tech- Power & Industrial Drives
 13. M.Tech- Power Electronics & Electrical Drives
 14. M.Tech- Power System Control & Automation
 15. M.Tech- Power Electronics & Drives
 16. M.Tech- Power Systems
 17. M.Tech- Power Systems Engineering
 18. M.Tech- High Voltage Engineering
 19. M.Tech- Power Electronics and Power Systems
 20. M.Tech- Power System and Control
 21. M.Tech- Power Electronics & Systems
 22. M.Tech- Electrical Machines and Drives
 23. M.Tech- Advanced Power Systems
 24. M.Tech- Power Systems with Emphasis on High Voltage Engineering
 25. M.Tech- Control Engineering
 26. M.Tech- Control Systems
 27. M.Tech- Electrical Power Engineering
 28. M.Tech- Power Engineering & Energy System
 29. M.Tech- Thermal Engineering
 30. M.Tech- CAD/CAM
 31. M.Tech- Machine Design
 32. M.Tech- Computer Aided Design and Manufacture
 33. M.Tech- Advanced Manufacturing Systems
 34. M.Tech-Computer Aided Analysis & Design
 35. M.Tech- Mechanical Engineering Design
 36. M.Tech- Systems and Signal Processing
 37. M.Tech- Digital Electronics and Communication Systems
 38. M.Tech- Electronics & Communications Engineering
 39. M.Tech- Communication Systems
 40. M.Tech- Communication Engineering & Signal Processing
 41. M.Tech- Microwave and Communication Engineering
 42. M.Tech- Telematics

43. M.Tech- Digital Systems & Computer Electronics
44. M.Tech- Embedded System
45. M.Tech- VLSI
46. M.Tech- VLSI Design
47. M.Tech- VLSI System Design
48. M.Tech- Embedded System & VLSI Design
49. M.Tech- VLSI & Embedded System
50. M.Tech- VLSI Design & Embedded Systems
51. M.Tech- Image Processing
52. M.Tech- Digital Image Processing
53. M.Tech- Computers & Communication
54. M.Tech- Computers & Communication Engineering
55. M.Tech- Instrumentation & Control Systems
56. M.Tech – VLSI & Micro Electronics
57. M.Tech – Digital Electronics & Communication Engineering
58. M.Tech- Embedded System & VLSI
59. M.Tech- Computer Science & Engineering
60. M.Tech- Computer Science
61. M.Tech- Computer Science & Technology
62. M.Tech- Computer Networks
63. M.Tech- Computer Networks & Information Security
64. M.Tech- Information Technology
65. M.Tech- Software Engineering
66. M.Tech- Neural Networks
67. M.Tech- Chemical Engineering
68. M.Tech- Biotechnology
69. M.Tech- Nano Technology
70. M.Tech- Food Processing
71. M.Tech- Avionics

and any other course as approved by AICTE/ University from time to time.

3.0 B. Departments offering M. Tech Programmes with specializations are noted below:

Civil Engg.	<ol style="list-style-type: none"> 1. M.Tech- Structural Engineering 2. M.Tech- Transportation Engineering 3. M.Tech- Infrastructure Engineering & Management 4. ME- Soil Mechanics and Foundation Engineering 5. M.Tech- Environmental Engineering 6. M.Tech-Geo-Informatics 7. M.Tech-Spatial Information Technology 8. M.Tech- Civil Engineering 9. M.Tech -Geo-Technical Engineering 10. M.Tech- Remote Sensing
EEE	<ol style="list-style-type: none"> 1. M.Tech- Power Electronics 2. M.Tech- Power & Industrial Drives 3. M.Tech- Power Electronics & Electrical Drives 4. M.Tech- Power System Control & Automation 5. M.Tech- Power Electronics & Drives 6. M.Tech- Power Systems 7. M.Tech- Power Systems Engineering 8. M.Tech- High Voltage Engineering 9. M.Tech- Power Electronics and Power Systems 10. M.Tech- Power System and Control 11. M.Tech- Power Electronics & Systems 12. M.Tech- Electrical Machines and Drives 13. M.Tech- Advanced Power Systems 14. M.Tech- Power Systems with Emphasis on High Voltage Engineering 15. M.Tech- Control Engineering 16. M.Tech- Control Systems 17. M.Tech- Electrical Power Engineering 18. M.Tech- Power Engineering & Energy System
ME	<ol style="list-style-type: none"> 1. M.Tech- Thermal Engineering 2. M.Tech- CAD/CAM 3. M.Tech- Machine Design 4. M.Tech- Computer Aided Design and Manufacture 5. M.Tech- Advanced Manufacturing Systems 6. M.Tech-Computer Aided Analysis & Design 7. M.Tech- Mechanical Engineering Design

ECE	<ol style="list-style-type: none"> 1. M.Tech- Systems and Signal Processing 2. M.Tech- Digital Electronics and Communication Systems 3. M.Tech- Electronics & Communications Engineering 4. M.Tech- Communication Systems 5. M.Tech- Communication Engineering & Signal Processing 6. M.Tech- Microwave and Communication Engineering 7. M.Tech- Telematics 8. M.Tech- Digital Systems & Computer Electronics 9. M.Tech- Embedded System 10. M.Tech- VLSI 11. M.Tech- VLSI Design 12. M.Tech- VLSI System Design 13. M.Tech- Embedded System & VLSI Design 14. M.Tech- VLSI & Embedded System 15. M.Tech- VLSI Design & Embedded Systems 16. M.Tech- Image Processing 17. M.Tech- Digital Image Processing 18. M.Tech- Computers & Communication 19. M.Tech- Computers & Communication Engineering 20. M.Tech- Instrumentation & Control Systems 21. M.Tech – VLSI & Micro Electronics 22. M.Tech – Digital Electronics & Communication Engineering 23. M.Tech- Embedded System & VLSI
CSE	<ol style="list-style-type: none"> 1. M.Tech- Computer Science & Engineering 2. M.Tech- Computer Science 3. M.Tech- Computer Science & Technology 4. M.Tech- Computer Networks 5. M.Tech- Computer Networks & Information Security 6. M.Tech- Information Technology 7. M.Tech- Software Engineering 8. M.Tech- Neural Networks
Others	<ol style="list-style-type: none"> 1. M.Tech- Chemical Engineering 2. M.Tech- Biotechnology 3. M.Tech- Nano Technology 4. M.Tech- Food Processing 5. M.Tech- Avionics

4.0 ATTENDANCE

- 4.1 A student shall be eligible to write University examinations if he acquires a minimum of 75% of attendance in aggregate of all the subjects.
- 4.2 Condonation of shortage of attendance in aggregate up to 10% (65% and above and below 75%) in each semester shall be granted by the College Academic Committee.
- 4.3 Shortage of Attendance below 65% in aggregate shall not be condoned.
- 4.4 Students whose shortage of attendance is not condoned in any semester are not eligible to write their end semester examination of that class.
- 4.5 A prescribed fee shall be payable towards condonation of shortage of attendance.
- 4.6 A student shall not be promoted to the next semester unless he satisfies the attendance requirement of the present semester, as applicable. They may seek readmission into that semester when offered next. If any candidate fulfills the attendance requirement in the present semester, he shall not be eligible for readmission into the same class.

5.0 EVALUATION

The performance of the candidate in each semester shall be evaluated subject-wise, with a maximum of 100 marks for theory and 100 marks for practicals, on the basis of Internal Evaluation and End Semester Examination.

- 5.1 For the theory subjects 60 marks shall be awarded based on the performance in the End Semester Examination and 40 marks shall be awarded based on the Internal Evaluation. The internal evaluation shall be made based on the **average** of the marks secured in the two Mid Term-Examinations conducted-one in the middle of the Semester and the other immediately after the completion of instruction. Each mid term examination shall be conducted for a total duration of 120 minutes with 4 questions (without choice) each question for 10 marks. End semester examination is conducted for 60 marks for 5 questions to be answered out of 8 questions.

- 5.2 For practical subjects, 60 marks shall be awarded based on the performance in the End Semester Examinations and 40 marks shall be awarded based on the day-to-day performance as Internal Marks.
- 5.3 There shall be two seminar presentations during III semester and IV semester. For seminar, a student under the supervision of a faculty member, shall collect the literature on a topic and critically review the literature and submit it to the department in a report form and shall make an oral presentation before the Project Review Committee consisting of Head of the Department, Supervisor and two other senior faculty members of the department. For each Seminar there will be only internal evaluation of 50 marks. A candidate has to secure a minimum of 50% of marks to be declared successful.
- 5.4 A candidate shall be deemed to have secured the minimum academic requirement in a subject if he secures a minimum of 40% of marks in the End semester Examination and a minimum aggregate of 50% of the total marks in the End Semester Examination and Internal Evaluation taken together.
- 5.5 In case the candidate does not secure the minimum academic requirement in any subject (as specified in 5.4) he has to reappear for the End semester Examination in that subject. A candidate shall be given one chance to re-register for each subject provided the internal marks secured by a candidate are less than 50% and has failed in the end examination. In such a case, the candidate must re-register for the subject(s) and secure the required minimum attendance. The candidate's attendance in the re-registered subject(s) shall be calculated separately to decide upon his eligibility for writing the end examination in those subject(s). In the event of the student taking another chance, his internal marks and end examination marks obtained in the previous attempt stand cancelled. For re-registration the candidates have to apply to the University through the college by paying the requisite fees and get approval from the University before the start of the semester in which re-registration is required.

- 5.6 In case the candidate secures less than the required attendance in any re registered subject (s), he shall not be permitted to write the End Examination in that subject. He shall again re-register the subject when next offered.
- 5.7 Laboratory examination for M. Tech. courses must be conducted with two Examiners, one of them being the Laboratory Class Teacher or teacher of the respective college and the second examiner shall be appointed by the university from the panel of examiners submitted by the respective college.

6.0 EVALUATION OF PROJECT/DISSERTATION WORK

Every candidate shall be required to submit a thesis or dissertation on a topic approved by the Project Review Committee.

- 6.1 A Project Review Committee (PRC) shall be constituted with Head of the Department and two other senior faculty members.
- 6.2 Registration of Project Work: A candidate is permitted to register for the project work after satisfying the attendance requirement of all the subjects, both theory and practical.
- 6.3 After satisfying 6.2, a candidate has to submit, in consultation with his project supervisor, the title, objective and plan of action of his project work for approval. The student can initiate the Project work, only after obtaining the approval from the Project Review Committee (PRC).
- 6.4 If a candidate wishes to change his supervisor or topic of the project, he can do so with the approval of the Project Review Committee (PRC). However, the Project Review Committee (PRC) shall examine whether or not the change of topic/supervisor leads to a major change of his initial plans of project proposal. If yes, his date of registration for the project work starts from the date of change of Supervisor or topic as the case may be.
- 6.5 A candidate shall submit his status report in two stages at least with a gap of 3 months between them.
- 6.6 The work on the project shall be initiated at the beginning of the II year and the duration of the project is two semesters. A candidate is permitted to submit Project Thesis only after

successful completion of theory and practical course with the approval of PRC not earlier than 40 weeks from the date of registration of the project work. The candidate has to pass all the theory and practical subjects before submission of the Thesis.

- 6.7 Three copies of the Project Thesis certified by the supervisor shall be submitted to the College/School/Institute.
- 6.8 The thesis shall be adjudicated by one examiner selected by the University. For this, the Principal of the College shall submit a panel of 5 examiners, eminent in that field, with the help of the guide concerned and head of the department.
- 6.9 If the report of the examiner is not favourable, the candidate shall revise and resubmit the Thesis, in the time frame as decided by the PRC. If the report of the examiner is unfavorable again, the thesis shall be summarily rejected. The candidate has to re-register for the project and complete the project within the stipulated time after taking the approval from the University.
- 6.10 If the report of the examiner is favourable, Viva-Voce examination shall be conducted by a board consisting of the Supervisor, Head of the Department and the examiner who adjudicated the Thesis. The Board shall jointly report the candidate's work as one of the following:
 - A. Excellent
 - B. Good
 - C. Satisfactory
 - D. Unsatisfactory

The Head of the Department shall coordinate and make arrangements for the conduct of Viva-Voce examination.

- 6.11 If the report of the Viva-Voce is unsatisfactory, the candidate shall retake the Viva-Voce examination only after three months. If he fails to get a satisfactory report at the second Viva-Voce examination, the candidate has to re-register for the project and complete the project within the stipulated time after taking the approval from the University.

7.0 AWARD OF DEGREE AND CLASS

After a student has satisfied the requirements prescribed for the completion of the program and is eligible for the award of M. Tech. Degree he shall be placed in one of the following four classes:

Class Awarded	% of marks to be secured
First Class with Distinction	70% and above (Without any Supplementary Appearance)
First Class	Below 70% but not less than 60% 70% and above (With any Supplementary Appearance)
Second Class	Below 60% but not less than 50%

The marks in internal evaluation and end examination shall be shown separately in the memorandum of marks.

8.0 WITHHOLDING OF RESULTS

If the student has not paid the dues, if any, to the university or if any case of indiscipline is pending against him, the result of the student will be withheld. His degree will be withheld in such cases.

4.0 TRANSITORY REGULATIONS (for R09)

- 9.1 Discontinued or detained candidates are eligible for re-admission into same or equivalent subjects at a time as and when offered.
- 9.2 The candidate who fails in any subject will be given two chances to pass the same subject; otherwise, he has to identify an equivalent subject as per R13 academic regulations.

10. GENERAL

- 10.1 Wherever the words “he”, “him”, “his”, occur in the regulations, they include “she”, “her”, “hers”.
- 10.2 The academic regulation should be read as a whole for the purpose of any interpretation.
- 10.3 In the case of any doubt or ambiguity in the interpretation of the above rules, the decision of the Vice-Chancellor is final.
- 10.4 The University may change or amend the academic regulations or syllabi at any time and the changes or amendments made shall be applicable to all the students with effect from the dates notified by the University.

MALPRACTICES RULES**DISCIPLINARY ACTION FOR / IMPROPER CONDUCT IN
EXAMINATIONS**

	Nature of Malpractices/ Improper conduct	Punishment
	<i>If the candidate:</i>	
1. (a)	Possesses or keeps accessible in examination hall, any paper, note book, programmable calculators, Cell phones, pager, palm computers or any other form of material concerned with or related to the subject of the examination (theory or practical) in which he is appearing but has not made use of (material shall include any marks on the body of the candidate which can be used as an aid in the subject of the examination)	Expulsion from the examination hall and cancellation of the performance in that subject only.
(b)	Gives assistance or guidance or receives it from any other candidate orally or by any other body language methods or communicates through cell phones with any candidate or persons in or outside the exam hall in respect of any matter.	Expulsion from the examination hall and cancellation of the performance in that subject only of all the candidates involved. In case of an outsider, he will be handed over to the police and a case is registered against him.
2.	Has copied in the examination hall from any paper, book, programmable calculators, palm computers or any other form of material relevant to the subject of the examination	Expulsion from the examination hall and cancellation of the performance in that subject and all other subjects the candidate has already appeared including practical examinations and project

	(theory or practical) in which the candidate is appearing.	work and shall not be permitted to appear for the remaining examinations of the subjects of that Semester/year. The Hall Ticket of the candidate is to be cancelled and sent to the University.
3.	Impersonates any other candidate in connection with the examination.	The candidate who has impersonated shall be expelled from examination hall. The candidate is also debarred and forfeits the seat. The performance of the original candidate who has been impersonated, shall be cancelled in all the subjects of the examination (including practicals and project work) already appeared and shall not be allowed to appear for examinations of the remaining subjects of that semester/year. The candidate is also debarred for two consecutive semesters from class work and all University examinations. The continuation of the course by the candidate is subject to the academic regulations in connection with forfeiture of seat. If the imposter is an outsider, he will be handed over to the police and a case is registered against him.
4.	Smuggles in the Answer book or additional sheet or takes out or arranges to send out the question paper during the examination or answer book or additional sheet, during or after	Expulsion from the examination hall and cancellation of performance in that subject and all the other subjects the candidate has already appeared including practical examinations and project work and

	the examination.	shall not be permitted for the remaining examinations of the subjects of that semester/year. The candidate is also debarred for two consecutive semesters from class work and all University examinations. The continuation of the course by the candidate is subject to the academic regulations in connection with forfeiture of seat.
5.	Uses objectionable, abusive or offensive language in the answer paper or in letters to the examiners or writes to the examiner requesting him to award pass marks.	Cancellation of the performance in that subject.
6.	Refuses to obey the orders of the Chief Superintendent/ Assistant – Superintendent / any officer on duty or misbehaves or creates disturbance of any kind in and around the examination hall or organizes a walk out or instigates others to walk out, or threatens the officer-in-charge or any person on duty in or outside the examination hall of any injury to his person or to any of his relations whether by words, either spoken or written or by signs or by visible representation, assaults the officer-in-charge, or any person on duty in or	In case of students of the college, they shall be expelled from examination halls and cancellation of their performance in that subject and all other subjects the candidate(s) has (have) already appeared and shall not be permitted to appear for the remaining examinations of the subjects of that semester/year. The candidates also are debarred and forfeit their seats. In case of outsiders, they will be handed over to the police and a police case is registered against them.

	<p>outside the examination hall or any of his relations, or indulges in any other act of misconduct or mischief which result in damage to or destruction of property in the examination hall or any part of the College campus or engages in any other act which in the opinion of the officer on duty amounts to use of unfair means or misconduct or has the tendency to disrupt the orderly conduct of the examination.</p>	
7.	<p>Leaves the exam hall taking away answer script or intentionally tears of the script or any part thereof inside or outside the examination hall.</p>	<p>Expulsion from the examination hall and cancellation of performance in that subject and all the other subjects the candidate has already appeared including practical examinations and project work and shall not be permitted for the remaining examinations of the subjects of that semester/year. The candidate is also debarred for two consecutive semesters from class work and all University examinations. The continuation of the course by the candidate is subject to the academic regulations in connection with forfeiture of seat.</p>
8.	<p>Possess any lethal weapon or firearm in the examination hall.</p>	<p>Expulsion from the examination hall and cancellation of the performance in that subject and all other subjects the candidate has already appeared including practical examinations and project work and shall not be permitted for the remaining</p>

		examinations of the subjects of that semester/year. The candidate is also debarred and forfeits the seat.
9.	If student of the college, who is not a candidate for the particular examination or any person not connected with the college indulges in any malpractice or improper conduct mentioned in clause 6 to 8.	Student of the colleges expulsion from the examination hall and cancellation of the performance in that subject and all other subjects the candidate has already appeared including practical examinations and project work and shall not be permitted for the remaining examinations of the subjects of that semester/year. The candidate is also debarred and forfeits the seat. Person(s) who do not belong to the College will be handed over to police and, a police case will be registered against them.
10.	Comes in a drunken condition to the examination hall.	Expulsion from the examination hall and cancellation of the performance in that subject and all other subjects the candidate has already appeared including practical examinations and project work and shall not be permitted for the remaining examinations of the subjects of that semester/year.
11.	Copying detected on the basis of internal evidence, such as, during valuation or during special scrutiny.	Cancellation of the performance in that subject and all other subjects the candidate has appeared including practical examinations and project work of that semester/year examinations.
12.	If any malpractice is detected which is not covered in the above clauses 1 to 11 shall be reported to the University for further action to award suitable punishment.	

Malpractices identified by squad or special invigilators

1. Punishments to the candidates as per the above guidelines.
2. Punishment for institutions : (if the squad reports that the college is also involved in encouraging malpractices)
 - (i) A show cause notice shall be issued to the college.
 - (ii) Impose a suitable fine on the college.
 - (iii) Shifting the examination centre from the college to another college for a specific period of not less than one year.



JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY: KAKINADA



KAKINADA-533003, Andhra Pradesh (India)






For Constituent Colleges and Affiliated Colleges of JNTUK

Ragging

Prohibition of ragging in educational institutions Act 26 of 1997

Salient Features

- ⇒ Ragging within or outside any educational institution is prohibited.
- ⇒ Ragging means doing an act which causes or is likely to cause Insult or Annoyance of Fear or Apprehension or Threat or Intimidation or outrage of modesty or Injury to a student

	Imprisonment upto		Fine Upto
Teasing, Embarrassing and Humiliation	 6 Months	+	Rs. 1,000/-
Assaulting or Using Criminal force or Criminal intimidation	 1 Year	+	Rs. 2,000/-
Wrongfully restraining or confining or causing hurt	 2 Years	+	Rs. 5,000/-
Causing grievous hurt, kidnapping or Abducts or rape or committing unnatural offence	 5 Years	+	Rs.10,000/-
Causing death or abetting suicide	 10 Months	+	Rs. 50,000/-

In Case of Emergency CALL TOLL FREE NO. : 1800 - 425 - 1288

LET US MAKE JNTUK RAGGING FREE UNIVERSITY



JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY: KAKINADA



KAKINADA-533003, Andhra Pradesh (India)
For Constituent Colleges and Affiliated Colleges of JNTUK

Ragging

ABSOLUTELY NO TO RAGGING

1. Ragging is prohibited as per Act 26 of A.P. Legislative Assembly, 1997.
2. Ragging entails heavy fines and/or imprisonment.
3. Ragging invokes suspension and dismissal from the College.
4. Outsiders are prohibited from entering the College and Hostel without permission.
5. Girl students must be in their hostel rooms by 7.00 p.m.
6. All the students must carry their Identity Card and show them when demanded
7. The Principal and the Wardens may visit the Hostels and inspect the rooms any time.



Jawaharlal Nehru Technological University Kakinada
For Constituent Colleges and Affiliated Colleges of JNTUK

In Case of Emergency CALL TOLL FREE NO. : 1800 - 425 - 1288

LET US MAKE JNTUK A RAGGING FREE UNIVERSITY

DEPARTMENT OF MECHANICAL ENGINEERING
M.Tech Specialization : CAD /CAM
COURSE STRUCTURE

I SEMESTER

S.NO	SUBJECT	L	P	C
1	INDUSTRIAL ROBOTICS	4	—	3
2	COMPUTER AIDED MANUFACTURING	4	—	3
3	SPECIAL MANUFACTURING PROCESSES	4		3
4	GEOMETRIC MODELING	4	—	3
5	ELECTIVE I COMPUTATIONAL METHODS IN ENGINEERING MECHANICAL VIBRATIONS NANO TECHNOLOGY	4	—	3
6	ELECTIVE II DESIGN FOR MANUFACTURING MECHATRONICS COMPUTER AIDED PROCESS PLANNING	4	—	3
7	ADVANCED CAD LAB	—	3	2
	TOTAL			20

II SEMESTER

1	SIMULATION MODELING OF MANUFACTURING SYSTEMS	4	—	3
2	OPTIMIZATION AND RELIABILITY	4	—	3
3	COMPUTER GRAPHICS	4	—	3
4	FINITE ELEMENT METHOD	4	—	3
5	ELECTIVE III QUALITY ENGINEERING IN MANUFACTURING FRACTURE MECHANICS CONCURRENT ENGINEERING	4	—	3
6	ELECTIVE IV MECHANICS AND MANUFACTURING			

	METHODS OF COMPOSITES MATERIALS TECHNOLOGY INTELLIGENT MANUFACTURING SYSTEMS	4	—	3
7	MODELING AND ANALYSIS OF MANUFACTURING PROCESSES LAB	—	6	4
	TOTAL			22

III SEMESTER

S.NO.	SUBJECT	L	P	C
1	COMPREHENSIVE VIVA	—	—	2
2	SEMINAR-I	—	—	2
3	PROJECT WORK PART – I	—	—	14
	TOTAL			18

IV SEMESTER

S.NO.	SUBJECT	L	P	C
1	SEMINAR-II	—	—	2
2	PROJECT WORK PART – II	—	—	18
	TOTAL			20

SYLLABUS

I - I	L	P	Credits
	4	-	3
INDUSTRIAL ROBOTICS			

UNIT-I

INTRODUCTION: Automation and Robotics, Robot anatomy, robot configuration, motions, joint notation, work volume, robot drive system, control system and dynamic performance, precision of movement.

CONTROL SYSTEM AND COMPONENTS: Basic concept and models controllers, control system analysis, robot activation and feedback components. Position sensors, velocity sensors, actuators sensors, power transmission system.

UNIT-II

MOTION ANALYSIS AND CONTROL: Manipulator kinematics, position representation, forward transformation, homogeneous transformation, manipulator path control, robot dynamics, configuration of robot controller.

UNIT-III

END EFFECTORS: Grippers-types, operation, mechanism, force analysis, tools as end effectors consideration in gripper selection and design. **SENSORS:** Desirable features, tactile, proximity and range sensors, uses of sensors in robotics.

MACHINE VISION: Functions, Sensing and Digitizing-imaging, Devices, Lighting techniques, Analog to digital signal conversion, image storage, Image processing and Analysis-image data reduction, Segmentation feature extraction. Object recognition, training the vision system, Robotics application.

UNIT-IV

ROBOT PROGRAMMING: Lead through programming, Robot programming as a path in space, Motion interpolation, WAIT, SINONAL AND DELAY commands, Branching capabilities and Limitations.

ROBOT LANGUAGES: Textual robot Languages, Generation, Robot language structures, Elements in function.

UNIT - V

ROBOT CELL DESIGN AND CONTROL: Robot cell layouts-Robot centered cell, In-line robot cell, Considerations in work design, Work and control, Inter locks, Error detection, Work cell controller.

ROBOT APPLICATION: Material transfer, Machine loading/unloading, Processing operation, Assembly and Inspection, Future Application.

TEXT BOOKS:

1. Industrial Robotics / Groover M P /Pearson Edu.
2. Introduction to Robotic Mechanics and Control by JJ Craig, Pearson, 3rd edition.

REFERENCES:

- 1 Robotics / Fu K S/ McGraw Hill.
- 2 Robotic Engineering / Richard D. Klafter, Prentice Hall
- 3 Robot Analysis and Intelligence / Asada and Slotine / Wiley Inter-Science.
- 4 Robot Dynamics & Control – Mark W. Spong and M. Vidyasagar / John Wiley
- 5 Introduction to Robotics by SK Saha, The McGrah Hill Company, 6th, 2012
- 6 Robotics and Control / Mittal R K & Nagrath I J / TMH

I - I	L	P	Credits
	4	-	3
COMPUTER AIDED MANUFACTURING			

UNIT-I

COMPUTER AIDED PROGRAMMING: General information, APT programming, Examples APT programming problems (2D machining only). NC programming on CAD/CAM systems, the design and implementation of post processors .Introduction to CAD/CAM software, Automatic Tool Path generation.

UNIT-II

TOOLING FOR CNC MACHINES: Interchangeable tooling system, preset and qualified tools, coolant fed tooling system, modular fixturing, quick change tooling system, automatic head changers. DNC Systems and Adaptive Control: Introduction, type of DNC systems, advantages and disadvantages of DNC, adaptive control with optimization, Adaptive control with constraints, Adaptive control of machining processes like turning, grinding.

UNIT-III

POST PROCESSORS FOR CNC: Introduction to Post Processors: The necessity of a Post Processor, the general structure of a Post Processor, the functions of a Post Processor, DAPP — based- Post Processor: Communication channels and major variables in the DAPP — based Post Processor, th creation of a DAPP — Based Post Processor.

UNIT-IV

MICRO CONTROLLERS: Introduction, Hardware components, I/O pins, ports, external memory:, counters, timers and serial data I/O interrupts. Selection of Micro Controllers, Embedded Controllers, Applications and Programming of Micro Controllers. Programming Logic Controllers (PLC' s): Introduction, Hardware components of PLC, System, basic structure, principle of operations, Programming mnemonics timers, Internal relays and counters, Applications of PLC's in CNC Machines.

UNIT - V

COMPUTER AIDED PROCESS PLANNING: Hybrid CAAP System, Computer Aided Inspection and quality control, Coordinate Measuring Machine, Limitations of CMM, Computer Aided Testing, Optical Inspection Methods, Artificial Intelligence and expert system: Artificial Neural Networks, Artificial Intelligence in CAD, Experts systems and its structures.

TEXT BOOKS:

1. Computer Control of Manufacturing Systems / Yoram Koren / Mc Graw Hill. 1983.
2. CAD/CAM Principles and Applications, P.N.Rao, TMH

REFERENCES:

1. Computer Aided Design Manufacturing – K. Lalit Narayan, K. Mallikarjuna Rao and M.M.M. Sarcar, PHI, 2008.
2. CAD / CAM Theory and Practice, / Ibrahim Zeid, TMH
3. CAD / CAM / CIM, Radhakrishnan and Subramanian, New Age
4. Principles of Computer Aided Design and Manufacturing, Farid Amirouche, Pearson
5. Computer Numerical Control Concepts and programming, Warren S Seames, Thomson.

I - I	L	P	Credits
	4	-	3
SPECIAL MANUFACTURING PROCESSES			

UNIT-I

SURFACE TREATMENT: Scope, Cleaners, Methods of cleaning, Surface coating types, and ceramic and organic methods of coating, economics of coating. Electro forming, Chemical vapour deposition, thermal spraying, Ion implantation, diffusion coating, Diamond coating and cladding.

UNIT-II

PROCESSING OF CERAMICS: Applications, characteristics, classification .Processing of particulate ceramics, Powder preparations, consolidation, Drying, sintering, Hot compaction, Area of application, finishing of ceramics. Processing of Composites: Composite Layers, Particulate and fiber reinforced composites, Elastomers, Reinforced plastics, MMC, CMC, Polymer matrix composites.

UNIT-III**FABRICATION OF MICROELECTRONIC DEVICES:**

Crystal growth and wafer preparation, Film Deposition oxidation, lithography, bonding and packaging, reliability and yield, Printed Circuit boards, computer aided design in micro electronics, surface mount technology, Integrated circuit economics.

UNIT-IV

ADVANCED MACHINING PROCESSES: EDM, WireEDM, ECM, LBM, EBM, AJM, WJM – Principle, working, limitations and applications.

UNIT-V

RAPID PROTOTYPING: Working Principles, Methods, Stereo Lithography, Laser Sintering, Fused Deposition Method, Applications and Limitations, Rapid tooling, Techniques of rapid manufacturing

TEXT BOOKS:

1. Manufacturing Engineering and Technology / Kalpakijian / Adisson Wesley, 1995.
2. Process and Materials of Manufacturing / R. A. Lindburg / 1th edition, PHI 1990.

REFERENCES:

- 1 Microelectronic packaging handbook / Rao. R. Thummala and Eugene, J. Rymaszewski / Van Nostrand Renihold,
- 2 MEMS & Micro Systems Design and manufacture / Tai — Run Hsu / TMGH
- 3 Advanced Machining Processes / V.K.Jain / Allied Publications.
- 4 Introduction to Manufacturing Processes / John A Schey / Mc Graw Hill.

I - I	L	P	Credits
	4	-	3
GEOMETRIC MODELING			

UNIT-I

Introduction: Definition, Explicit and implicit equations, parametric equations.

UNIT-II

Cubic Splines-1: Algebraic and geometric form of cubic spline, tangent vectors, parametric space of a curve, blending functions, four point form, reparametrization, truncating and subdividing of curves. Graphic construction and interpretation, composite pc curves.

UNIT-III

Bezier Curves: Bernstein basis, equations of Bezier curves, properties, derivatives.

B-Spline Curves: B-Spline basis, equations, knot vectors, properties, and derivatives.

UNIT-IV

Surfaces: Bicubic surfaces, Coon's surfaces, Bezier surfaces, B-Spline surfaces, surfaces of revolutions, Sweep surfaces, ruled surfaces, tabulated cylinder, bilinear surfaces, Gaussian curvature.

UNIT-V

Solids: Tricubic solid, Algebraic and geometric form.

Solid modeling concepts: Wire frames, Boundary representation, Half space modeling, spatial cell, cell decomposition, classification problem.

TEXT BOOKS:

1. CAD/CAM by Ibrahim Zeid, Tata McGraw Hill.
2. Elements of Computer Graphics by Roger & Adams Tata McGraw Hill.

REFERENCES:

1. Geometric Modeling by Micheal E. Mortenson, McGraw Hill Publishers
2. Computer Aided Design and Manufacturing, K.Lalit Narayan, K.Mallikarjuna Rao, MMM Sarcar, PHI Publishers

I - I	L	P	Credits
	4	-	3
(ELECTIVE I) COMPUTATIONAL METHODS IN ENGINEERING			

UNIT-I

Introduction to numerical methods applied to engineering problems: Examples, solving sets of equations – Matrix notation – Determinants and inversion – Iterative methods – Relaxation methods – System of non-linear equations. Least square approximation fitting of non-linear curves by least squares – regression analysis- multiple linear regression, non linear regression - computer programs.

UNIT-II

Boundry value problems and charecteristic value problems: Shooting method – Solution through a set of equations – Derivative boundary conditions – Rayleigh – Ritz method – Characteristic value problems.

UNIT-III

Transformation Techniques: Continuous fourier series, frequency and time domains, laplace transform, fourier integral and transform, discrete fourier transform (DFT), Fast fourier transform (FFT).

UNIT-IV

Numerical solutions of partial differential equations: Laplace's equations – Representations as a difference equation – Iterative methods for Laplace's equations – poisson equation – Examples – Derivative boundary conditions – Irregular and non – rectangular grids – Matrix patterns, sparseness – ADI method – Finite element method.

UNIT-V

Partial differential equations: Explicit method – Crank-Nickelson method – Derivative boundary condition – Stability and convergence criteria. Solving wave equation by finite differences-stability of numerical method –method of characteristics-wave equation in two space dimensions-computer programs.

TEXT BOOKS:

1. Steven C.Chapra, Raymond P.Canale “Numerical Methods for Engineers” Tata Mc-Graw Hill
2. Curtis F.Gerald, Partick.O.Wheatly,”Applied numerical analysis”Addison-Wesley,1989
3. Douglas J.Faires,Riched Burden”Numerical methods”, Brooks/Cole publishing company,1998.Second edition.

REFERENCES:

1. Ward Cheney and David Kincaid “Numerical mathematics and computing” Brooks/Cole publishing company1999, Fourth edition.
2. Riley K.F. M.P.Hobson and Bence S.J,”Mathematical methods for physics and engineering”, Cambridge University press,1999.
3. Kreysis, Advanced Mathematics

I - I	L	P	Credits
	4	-	3
(ELECTIVE I) MECHANICAL VIBRATIONS			

UNIT-I

Single degree of Freedom systems: Undamped and damped free vibrations; forced vibrations ; coulomb damping; Response to harmonic excitation; rotating unbalance and support excitation, Vibration isolation and transmissibility. Response to Non Periodic Excitations: unit Impulse, unit step and unit Ramp functions; response to arbitrary excitations, The Convolution Integral; shock spectrum; System response by the Laplace Transformation method.

UNIT-II

Multi degree freedom systems: Principal modes – undamped and damped free and forced vibrations ; undamped vibration absorbers, Matrix formulation, stiffness and flexibility influence coefficients; Eigen value problem; normal modes and their properties; Free and forced vibration by Modal analysis; Method of matrix inversion; Torsional vibrations of multi – rotor systems and geared systems; Discrete-Time systems.

UNIT-III

Numerical Methods: Rayleigh's, Stodola's, Matrix iteration, Rayleigh-Ritz Method and Holzer's methods

UNIT-IV

Experimental Methods: Vibrometers, velocity meters & accelerometers

UNIT-V

Application of concepts: Free vibration of strings–longitudinal oscillations of bars-transverse vibrations of beams- Torsional vibrations of shafts. Critical speeds without and with damping, secondary critical speed.

TEXT BOOKS:

1. Elements of Vibration Analysis by Meirovitch.
2. Mechanical Vibrations by G.K. Groover.

REFERENCES:

1. Vibrations by W.T. Thomson
2. Mechanical Vibrations – Schaum series.
3. Vibration problems in Engineering by S.P. Timoshenko.
4. Mechanical Vibrations V.Ram Murthy.

I - I	L	P	Credits
	4	-	3
(ELECTIVE I) NANO TECHNOLOGY			

UNIT-I**Introduction**

Size and shape dependence of material properties at the nanoscale, why is small good?, limits to smallness, scaling relations, can nanorobots walk and nanoplanes fly? Nanoscale elements in conventional technologies, Mechanics at nanoscale, Enhancement of mechanical properties with decreasing size, Nanoelectromechanical systems, nanomachines, Nanofluidics, filtration, sorting, Molecular motors.

UNIT-II

Top-down and bottom-up nanofabrication, The Intel-IBM approach to nanotechnology: lithography, etching, ion implantation, thin film deposition, Electron beam lithography, Soft lithography: nanoimprinting and microcontact printing, Solution/plasma-phase nanofabrication, sol-gel methods, template techniques.

UNIT-III

Imaging/characterization of nanostructures, General considerations for imaging, Scanning probe techniques: SEM, STM, AFM, NSOM.

UNIT-IV

Metal and semiconductor nanoparticles, Synthesis, stability, control of size, Optical and electronic properties, Ultra-sensitive imaging and detection with nanoparticles, bioengineering applications, Catalysis. Semiconductor and metal nanowires Vapor/liquid/solid growth and other synthesis techniques, Nanowire transistors and sensors.

UNIT-V**Carbon nanotubes**

Structure and synthesis, Electronic, vibrational, and mechanical properties, How can C nanotubes enable faster computers, brighter TV screens, and stronger mechanical reinforcement?

TEXT BOOKS:

1. Nanoscale Science and Technology by Kelsall, Hamley, and Geoghegan, Wiley (2005)
2. Introduction to Nanoscale Science and Technology by Di Ventra, Evoy, and Heflin, Kluwer Academic Publishers (2004).

REFERENCES:

1. Introduction to Nanotechnology by Poole and Owens, Wiley (2003)
2. Nanochemistry: A Chemical Approach to Nanomaterials, Ozin and Arsenault, RSC Publishing (2006).

I - I	L	P	Credits
	4	-	3
(ELECTIVE II) DESIGN FOR MANUFACTURING			

UNIT-I

Introduction: Design philosophy-steps in design process-general design rules for manufacturability-basic principles of designing for economical production-creativity in design.

UNIT-II

Machining processes: Overview of various machining processes-general design rules for machining-dimensional tolerance and surface roughness-Design for machining – ease –redesigning of components for machining ease with suitable examples. General design recommendations for machined parts.

UNIT-III

Metal casting: Appraisal of various casting processes, selection of casting process,-general design considerations for casting-casting tolerance-use of solidification, simulation in casting design-product design rules for sand casting.

UNIT-IV

Metal joining: Appraisal of various welding processes, factors in design of weldments – general design guidelines-pre and post treatment of welds-effects of thermal stresses in weld joints-design of brazed joints. Forging: Design factors for forging – closed die forging design – parting lines of dies – drop forging die design – general design recommendations.

UNIT-V

Extrusion & Sheet metal work: Design guide lines extruded sections-design principles for punching, blanking, bending, deep drawing-Keeler Goodman forging line diagram – component design for blanking.

Plastics: Visco elastic and creep behavior in plastics-design guidelines for plastic components-design considerations for injection moulding – design guidelines for machining and joining of plastics.

TEXT BOOKS:

1. Design for manufacture, John cobert, Adisson Wesley. 1995
2. Design for Manufacture by Boothroyd,
3. Design for manufacture, James Bralla

REFERENCE:

1. ASM Hand book Vol.20

I - I	L	P	Credits
	4	-	3
(ELECTIVE II) MECHATRONICS			

UNIT-I

Mechatronics systems, elements, levels of mechatronics system, Mechatronics design process, system, measurement systems, control systems, microprocessor-based controllers, advantages and disadvantages of mechatronics systems. Sensors and transducers, types, displacement, position, proximity, velocity, motion , force, acceleration, torque, fluid pressure, liquid flow, liquid level, temperature and light sensors.

UNIT-II

Solid state electronic devices, PN junction diode, BJT, FET, DIA and TRIAC. Analog signal conditioning, amplifiers, filtering. Introduction to MEMS & typical applications.

UNIT-III

Hydraulic and pneumatic actuating systems, Fluid systems, Hydraulic and pneumatic systems, components, control valves, electro-pneumatic, hydro-pneumatic, electro-hydraulic servo systems:

Mechanical actuating systems and electrical actuating systems.

UNIT-IV

Digital electronics and systems, digital logic control, micro processors and micro controllers, programming, process controllers, programmable logic controllers, PLCs versus computers, application of PLCs for control.

UNIT-V

System and interfacing and data acquisition, DAQS , SCADA, A to D and D to A conversions; Dynamic models and analogies, System response. Design of mechatronics systems & future trends.

TEXT BOOKS:

1. MECHATRONICS Integrated Mechanical Electronics Systems/KP Ramachandran & GK Vijaya Raghavan/WILEY India Edition/2008
2. Mechatronics Electronics Control Systems in Mechanical and Electrical Engineering by W Bolton, Pearson Education Press, 3rd edition, 2005.

REFERENCES:

- 1 Mechatronics Source Book by Newton C Braga, Thomson Publications, Chennai.
- 2 Mechatronics – N. Shanmugam / Anuradha Agencies Publishers.
- 3 Mechatronics System Design / Devdas shetty/Richard/Thomson.
- 4 Mechatronics/M.D.Singh/J.G.Joshi/PHI.
- 5 Mechatronics – Electronic Control Systems in Mechanical and Electrical Engg. 4th Edition, Pearson, 2012 W. Bolton
- 6 Mechatronics – Principles and Application Godfrey C. Onwubolu, Wlsevier, 2006 Indian print

I - I	L	P	Credits
	4	-	3
(ELECTIVE II)			
COMPUTER AIDED PROCESS PLANNING			

UNIT-I

Introduction to CAPP: Information requirement for process planning system, Role of process planning, advantages of conventional process planning over CAPP, Structure of Automated process planning system, feature recognition, methods.

UNIT-II

Generative CAPP system: Importance, principle of Generative CAPP system, automation of logical decisions, Knowledge based systems, Inference Engine, implementation, benefits.

Retrieval CAPP system: Significance, group technology, structure, relative advantages, implementation, and applications.

UNIT-III

Selection of manufacturing sequence: Significance, alternative manufacturing processes, reduction of total set-up cost for a particular sequence, quantitative methods for optimal selection, examples.

Determination of machining parameters: reasons for optimal selection of machining parameters, effect of parameters on production rate, cost and surface quality, different approaches, advantages of mathematical approach over conventional approach, solving optimization models of machining processes.

UNIT-IV

Determination of manufacturing tolerances: design tolerances, manufacturing tolerances, methods of tolerance allocation, sequential approach, integration of design and manufacturing tolerances, advantages of integrated approach over sequential approach.

UNIT-V

Generation of tool path: Simulation of machining processes, NC tool path generation, graphical implementation, determination of optimal index positions for executing fixed sequence, quantitative methods.

Implementation techniques for CAPP: MIPLAN system, Computer programming languages for CAPP, criteria for selecting a CAPP system and benefits of CAPP. Computer integrated planning systems, and Capacity planning system.

TEXTBOOK:

1. Computer Aided Process Planning – Joseph Tulkoff, SME Publications
2. Computer Aided Process Planning – Hsu-Pin Wang, Jian-Kang Li, Elsevier

REFERENCES:

1. Automation , Production systems and Computer Integrated Manufacturing System – Mikell P.Groover
2. Computer Aided Design and Manufacturing – Dr.Sadhu Singh.
3. Computer Aided Engineering – David Bedworth

I - I	L	P	Credits
	-	3	2
ADVANCED CAD LAB			

Students shall carry out the modeling and FE analysis of the following to predict deflection and stress distributions :

1. Trussess – 2D and 3D
2. Beams
3. Plate with Plane stress condition
4. Plate with Plane strain condition
5. Cylinders – Axi-symmetric condition
6. Natural frequencies of Beam

I - II	L	P	Credits
	4	-	3
SIMULATION MODELING OF MANUFACTURING SYSTEMS			

UNIT-I

System - ways to analyze the system - Model - types of models - Simulation - Definition - Types of simulation models - steps involved in simulation - Advantages & Disadvantages. Parameter estimation - estimator - properties - estimate - point estimate - confidence interval estimates - independent - dependent - hypothesis - types of hypothesis-step - types 1& 2 errors - Framing - string law of large numbers.

UNIT-II

Building of Simulation model validation - verification - credibility - their timing - principles of valid simulation Modeling - Techniques for verification - statistical procedures for developing credible model. Modeling of stochastic input elements - importance - various procedures - theoretical distribution - continuous - discrete their suitability in modeling.

UNIT- III

Generation of random variables - factors for selection methods - inverse transform - composition - convolution - acceptance - rejection - generation of random variables - exponential - uniform - weibull - normal Bernoullie - Binomial uniform - poisson - Simulation languages - comparison of simulation languages with general purpose languages Simulation languages vs Simulators - software features - statistical capabilities - G P S S - S1MAN- SIMSCRIPT - Simulation of WMJI queue - comparison of simulation languages.

UNIT-IV

Output data analysis - Types of Simulation w. r. t output data analysis - warm up period- Welch algorithm - Approaches for Steady - State Analysis - replication - Batch means methods - corn pan Sons.

UNIT - V

Applications of Simulation - flow shop system - job shop system - M/MI1 queues with infinite and finite capacities - Simple fixed period inventory system – New boy paper problem.

TEXT BOOKS:

1. Simulation Modelling and Analysis / Law, A.M.& Kelton / Mc Graw Hill, Edition/ New York, 1991.
2. Simulation of Manufacturing Systems / Carrie A. / Wiley, NY, 1990.

REFERENCES:

1. Discrete Event System Simulation / Banks J. & Carson J.S., PH / Englewood Cliffs N/ 1984.
2. A Course in Simulation / Ross, S.M., McMillan, NY, 1990.
3. Simulation Modelling and SIMNET/ Taha HA. / PH, Englewood Cliffs, NJ, 1987

I – II	L	P	Credits
	4	-	3
OPTIMIZATION AND RELIABILITY			

UNIT-I

Classical optimization techniques: Single variable optimization with and without constraints, multi – variable optimization without constraints, multi – variable optimization with constraints – method of Lagrange multipliers, Kuhn-Tucker conditions.

UNIT-II

Numerical methods for optimization: Nelder Mead’s Simplex search method, Gradient of a function, Steepest descent method, Newton’s method, types of penalty methods for handling constraints.

UNIT-III

Genetic algorithm (GA) : Differences and similarities between conventional and evolutionary algorithms, working principle, reproduction, crossover, mutation, termination criteria, different reproduction and crossover operators, GA for constrained optimization, draw backs of GA,

Genetic Programming (GP): Principles of genetic programming, terminal sets, functional sets, differences between GA & GP, random population generation, solving differential equations using GP.

UNIT-IV

Multi-Objective GA: Pareto’s analysis, Non-dominated front, multi – objective GA, Non-dominated sorted GA, convergence criterion, applications of multi-objective problems .

UNITV

Applications of Optimization in Design and Manufacturing systems: Some typical applications like optimization of path synthesis of a four-bar mechanism, minimization of weight of a cantilever beam, optimization of springs and gears, general optimization model of a machining process, optimization of arc welding parameters, and general procedure in optimizing machining operations sequence.

TEXT BOOKS:

1. Optimal design – Jasbir Arora, Mc Graw Hill (International) Publishers
2. Optimization for Engineering Design – Kalyanmoy Deb, PHI Publishers
3. Engineering Optimization – S.S.Rao, New Age Publishers

REFERENCES:

1. Genetic algorithms in Search, Optimization, and Machine learning – D.E.Goldberg, Addison-Wesley Publishers
2. Genetic Programming- Koza
3. Multi objective Genetic algorithms - Kalyanmoy Deb, PHI Publishers

I - II	L	P	Credits
	4	-	3
COMPUTER GRAPHICS			

UNIT-I

Introduction to computer graphics: Color CRT raster scan monitors, plasma display & liquid crystal display monitors, computer input devices, hard copy devices.

UNIT-II

Raster scan graphics: Line drawing algorithms – DDA & Bresenham algorithms, circle generation, general function rasterization, displaying lines, characters and polygons.

Filling algorithms: polygon filling, edge fill algorithm, seed fill algorithm, fundamentals of antialiasing and half toning.

UNIT-III

Line CLIPPING: Simple visibility algorithm, Cohen-Sutherland subdivision line clipping algorithm, mid point sub division algorithm.

Polygon clipping: polygon clipping, reentrant polygon clipping – Sutherland – Hodgeman algorithm, character clipping, 3D- clipping.

UNIT-IV

Transformations: Cartesian and homogeneous coordinate systems two dimensional and three dimensional transformations – scaling, rotation, Shearing, Zooming, viewing transformation, reflection, rotation about an axis, concatenation.

UNIT-V

Rendering: Hidden line removal algorithms, surface removal algorithms, painters, Warnock, Z-buffer algorithm.

Shading algorithms: Constant intensity algorithm, Phong's shading algorithm, gourand shading algorithm, Comparison of shading algorithms.

TEXT BOOKS:

1. Procedural elements for computer graphics-D.F.Rogers, Tata McGraw-Hill.
2. Computer Graphics-Donald Hearn & M.P. Bakers.
3. Computer graphics-Harrington.

I – II	L	P	Credits
	4	-	3
FINITE ELEMENT METHOD			

UNIT-I

Formulation Techniques: Methodology, Engineering problems and governing differential equations, finite elements, Variational methods-potential energy method, Raleigh Ritz method, strong and weak forms, Galerkin and weighted residual methods, calculus of variations, Essential and natural boundary conditions.

UNIT-II

One-dimensional elements: Bar, trusses, beams and frames, displacements, stresses and temperature effects.

UNIT-III

Two dimensional problems: CST, LST, four noded and eight noded rectangular elements, Lagrange basis for triangles and rectangles, serendipity interpolation functions. Axisymmetric Problems: Axisymmetric formulations, Element matrices, boundary conditions. Heat Transfer problems: Conduction and convection, examples: - two-dimensional fin.

UNIT-IV

Isoparametric formulation: Concepts, sub parametric, super parametric elements, numerical integration, Requirements for convergence, h-refinement and p-refinement, complete and incomplete interpolation functions, pascal's triangle, Patch test.

UNIT-V

Finite elements in Structural Analysis: Static and dynamic analysis, eigen value problems, and their solution methods, case studies using commercial finite element packages.

TEXTBOOK:

1. Finite element methods by Chandrubatla & Belagondur.

REFERENCES:

1. J.N. Reddy, Finite element method in Heat transfer and fluid dynamics, CRC press,1994
2. Zienkiwicz O.C. & R. L. Taylor, Finite Element Method, McGraw-Hill,1983.
3. K. J. Bathe, Finite element procedures, Prentice-Hall, 1996

I – II	L	P	Credits
	4	-	3
(ELECTIVE III)			
QUALITY ENGINEERING IN MANUFACTURING			

UNIT-I

QUALITY VALUE AND ENGINEERING: An overall quality system, quality engineering in production design, quality engineering in design of production processes. Loss Function and Quality Level: Derivation and use of quadratle loss function, economic consequences of tightening tolerances as a means to improve quality, evaluations and types tolerances.(N-type,S-type and L-type)

UNITII:

TOLERANCE DESIGN AND TOLERANCING: Functional limits, tolerance design for N-type. L-type and S-type characteristics, tolerance allocation for multiple components. Parameter and Tolerance Design: Introduction to parameter design, signal to noise ratios, Parameter design strategy, some of the case studies on parameter and tolerance designs.

UNIT–III

ANALYSIS OF VARIANCE (ANOVA): Introduction to ANOVA, Need for ANOVA, NO-way ANOVA, One-way ANOVA, Two-way ANOVA, Critique of F-test, ANOVA for four level factors, multiple level factors.

UNIT-IV

ORTHOGONAL ARRAYS: Typical test strategies, better test strategies, efficient test strategies, steps in designing, conducting and analyzing an experiment. Interpolation of Experimental Results: Interpretation methods, percent contributor, estimating the mean.

UNIT - V

SIX SIGMA AND THE TECHNICAL SYSTEM: Six sigma DMAIC methodology, tools for process improvement, six sigma in services and small organizations, statistical foundations, statistical methodology.

TEXTBOOK:

1. Taguchi Techniques for Quality Engineering / Phillip J. Ross / McGraw Hill/ Intl. II Edition, 1995.

REFERENCES:

1. Quality Engineering in Production systems by G. Taguchi, A. Elsayed et al, McGraw Hill Intl. Pub 1989.
2. Taguchi Methods explained: Practical steps to Robust Design / Papan P. Bagchi / Prentice Hall Pvt. Ltd., New Delhi.

I – II	L	P	Credits
	4	-	3
(ELECTIVE III) FRACTURE MECHANICS			

UNIT-I

Introduction: Prediction of mechanical failure. Macroscopic failure modes; brittle and ductile behaviour. Fracture in brittle and ductile materials – characteristics of fracture surfaces; inter-granular and intra-granular failure, cleavage and micro-ductility, growth of fatigue cracks, The ductile/brittle fracture transition temperature for notched and unnotched components. Fracture at elevated temperature.

UNIT-II

Griffiths analysis: Concept of energy release rate, G , and fracture energy, R . Modification for ductile materials, loading conditions. Concept of R curves.

Linear Elastic Fracture Mechanics, (LEFM). Three loading modes and the state of stress ahead of the crack tip, stress concentration factor, stress intensity factor and the material parameter the critical stress intensity factor, crack tip plasticity, effect of thickness on fracture toughness.

UNIT-III

Elastic-Plastic Fracture Mechanics; (EPFM). The definition of alternative failure prediction parameters, Crack Tip Opening Displacement, and the J integral. Measurement of parameters and examples of use.

UNIT-IV

Fatigue: Definition of terms used to describe fatigue cycles, High Cycle Fatigue, Low Cycle Fatigue, mean stress R ratio, strain and load control. S-N curves. Goodmans rule and Miners rule. Micromechanisms of fatigue damage, fatigue limits and initiation and propagation control, leading to a consideration of factors enhancing fatigue resistance. Total life and damage tolerant approaches to life prediction.

UNIT-V

Creep deformation: The evolution of creep damage, primary, secondary and tertiary creep. Micro-mechanisms of creep in materials and the role of diffusion. Ashby creep deformation maps. Stress dependence of creep – power law dependence. Comparison of creep performance under different conditions – extrapolation and the use of Larson-Miller parameters. Creep-fatigue interactions. Examples.

TEXT BOOKS:

1. T.L. Anderson, Fracture Mechanics Fundamentals and Applications, 2nd Ed. CRC press, (1995)
2. J.F. Knott, Fundamentals of Fracture Mechanics, Butterworths (1973)
3. G. E. Dieter, Mechanical Metallurgy, McGraw Hill, (1988)
4. S. Suresh, Fatigue of Materials, Cambridge University Press, (1998)

REFERENCES:

1. B. Lawn, Fracture of Brittle Solids, Cambridge Solid State Science Series 2nd ed 1993.
2. J.F. Knott, P Withey, Worked examples in Fracture Mechanics, Institute of Materials.
3. H.L. Ewald and R.J.H. Wanhill Fracture Mechanics, Edward Arnold, (1984).
4. L.B. Freund and S. Suresh, Thin Film Materials Cambridge University Press, (2003).
5. D.C. Stouffer and L.T. Dame, Inelastic Deformation of Metals, Wiley (1996)

I – II	L	P	Credits
	4	-	3
(ELECTIVE III) CONCURRENT ENGINEERING			

UNIT-I**INTRODUCTION**

Extensive definition of CE - CE design methodologies - Organizing for CE - CE tool box collaborative product development

USE OF INFORMATION TECHNOLOGY

IT support - Solid modeling - Product data management - Collaborative product commerce - Artificial Intelligence - Expert systems - Software hardware co-design.

UNIT-II**DESIGN STAGE**

Life-cycle design of products - opportunity for manufacturing enterprises - modality of Concurrent Engineering Design –

Automated analysis idealization control - Concurrent engineering in optimal structural design - Real time constraints.

UNIT-III**MANUFACTURING CONCEPTS AND ANALYSIS**

Manufacturing competitiveness - Checking the design process - conceptual design mechanism – Qualitative, physical approach - An intelligent design for manufacturing system –

UNIT-IV

JIT system - low inventory - modular - Modeling and reasoning for computer based assembly planning - Design of Automated manufacturing.

PROJECT MANAGEMENT

Life Cycle semi realization - design for economics - evaluation of design for manufacturing cost

UNIT-V

Concurrent mechanical design - decomposition in concurrent design - negotiation in concurrent engineering design studies - product realization taxonomy - plan for Project Management on new product development – bottleneck technology development.

TEXT BOOKS:

1. Integrated Product Development / Anderson MM and Hein, L. Berlin, Springer, 1987.
2. Concurrent Engineering: Automation Tools and Technology / Andrew Kusaik, John Wiley.

REFERENCES:

1. Design for Concurrent Engineering / Cleetus, J, Concurrent Engg. Research Centre, Morgantown, WV, 1992.
2. Concurrent Engineering Fundamentals: Integrated Product Development/ Prasad, Prentice Hall, 1996.
3. Successful Implementation of Concurrent Product and Process / Sammy G Sinha, Wiley, John and Sons Inc., 1998.

I – II	L	P	Credits
	4	-	3

(ELECTIVE IV)
MECHANICS AND MANUFACTURING
METHODS OF COMPOSITES

UNIT – I

Basic concepts and characteristics: Geometric and Physical definitions, natural and man-made composites, Aerospace and structural applications, types and classification of composites, Fibres- Glass, Silica, Kevlar, carbon, boron, silicon carbide, and born carbide fibres. Particulate composites, Polymer composites, Thermoplastics, Thermosets, Metal matrix and ceramic composites.

UNIT – II

Micromechanics: Unidirectional composites, constituent materials and properties, elastic properties of a lamina, properties of typical composite materials, laminate characteristics and configurations. Characterization of composite properties.

Coordinate transformations: Hooke's law for different types of materials, Hooke's law for two dimensional unidirectional lamina, Transformation of stress and strain, Numerical examples of stress strain transformation, Graphic interpretation of stress – strain relations. Off - axis, stiffness modulus, off - axis compliance.

UNIT – III

Elastic behavior of unidirectional composites: Elastic constants of lamina, relation ship between engineering constants and reduced stiffness and compliances, analysis of laminated composites, constitutive relations.

Strength of unidirectional lamina: Micro mechanics of failure, Failure mechanisms, Strength of an orthotropic lamina, Strength of a lamina under tension and shear maximum stress and strain criteria, application to design. The failure envelope, first ply failure, free-edge effects. Micro mechanical predictions of elastic constants.

UNIT – IV

Analysis of laminated composite plates Introduction, thin plate theory, specially orthotropic plate, cross and angle ply laminated plates, problems using thin plate theory.

UNIT – V

Manufacturing methods: Autoclave, tape production, moulding methods, filament winding, man layup, pultrusion, RTM.

TEXT BOOKS:

1. R. M. Jones, Mechanics of Composite Materials, Mc Graw Hill Company, New York, 1975.
2. Engineering Mechanics of Composite Materials by Isaac and M. Daniel, Oxford University Press, 1994.

REFERENCES:

1. B. D. Agarwal and L. J. Broutman, Analysis and performance of fibre Composites, Wiley-Interscience, New York, 1980.
2. L. R. Calcote, Analysis of Laminated Composite Structures, Van Nostrand Rainfold, New York, 1969.

I – II	L	P	Credits
	4	-	3
(ELECTIVE IV) MATERIALS TECHNOLOGY			

UNIT-I

Elasticity in metals and polymers, mechanism of plastic deformation, role of dislocations, yield stress, shear strength of perfect and real crystals, strengthening mechanism, work hardening, solid solution, grain boundary strengthening. Poly phase mixture, precipitation, particle, fiber and dispersion strengthening, effect of temperature, strain and strain rate on plastic behavior, super plasticity, deformation of non crystalline material

UNIT-II

Griffth's Theory, stress intensity factor and fracture Toughness, Toughening Mechanisms, Ductile and Brittle transition in steel, High Temperature Fracture, Creep, Larson – Miller parameter, Deformation and Fracture mechanism maps.

UNIT-III

Fatigue, Low and High cycle fatigue test, Crack Initiation and Propagation mechanism and paris Law, Effect of surface and metallurgical parameters on Fatigue, Fracture of non-metallic materials, fatigue analysis, Sources of failure, procedure of failure analysis. Motivation for selection, cost basis and service requirements, Selection for Mechanical Properties, Strength, Toughness, Fatigue and Creep.

UNIT-IV

MODERN METALLIC MATERIALS: Dual Steels, Micro alloyed, High Strength Low alloy (HSLA) Steel, Transformation induced plasticity (TRIP) Steel, Maraging Steel, Inter metallics, Ni and Ti Aluminides. Processing and applications of Smart Materials, Shape Memory alloys, Metallic Glass Quasi Crystal and Nano Crystalline Materials.

UNIT-V

NONMETALLIC MATERIALS: Polymeric materials and their molecular structures, Production Techniques for Fibers, Foams, Adhesives and Coatings, structure, Properties and Applications of Engineering Polymers, Advanced Structural Ceramics WC, TiC, TaC, Al₂O₃, SiC, Si₃N₄, CBN and Diamond – properties, Processing and applications.

TEXT BOOKS:

1. Mechanical Behavior of Materials/Thomas H. Courtney/ McGraw Hill/ 2nd Edition/2000
2. Mechanical Metallurgy/George E. Dieter/McGraw Hill, 1998.

REFERENCES:

- 1 Selection and use of Engineering Materials 3e/Charles J.A/Butterworth Heiremann.
- 2 Engineering Materials Technology/James A Jacob Thomas F Kilduff/ Pearson
- 3 Material Science and Engineering/William D Callister/John Wiley and Sons

I – II	L	P	Credits
	4	-	3
(ELECTIVE IV)			
INTELLIGENT MANUFACTURING SYSTEMS			

UNIT-I

COMPUTER INTEGRATED MANUFACTURING SYSTEMS: structure and functional areas of cim system- CAD, CAPP, CAM, CAQC, ASRS. Advantages of CIM. Manufacturing Communication Systems - MAP/TOP, OSI Model, Data Redundancy, Top- down and Bottom-up Approach, Volume of Information. Intelligent Manufacturing System Components, System Architecture and Data Flow, System Operation.

UNIT-II

COMPONENTS OF KNOWLEDGE BASED SYSTEMS - Basic Components of Knowledge Based Systems, Knowledge Representation, Comparison of Knowledge Representation Schemes, Inference Engine, Knowledge Acquisition.

UNIT-III

MACHINE LEARNING - Concept of Artificial Intelligence, Conceptual Learning, Artificial Neural Networks - Biological Neuron, Artificial Neuron, Types of Neural Networks, Applications in Manufacturing.

UNIT-IV

AUTOMATED PROCESS PLANNING - Variant Approach, Generative Approach, Expert Systems for Process Planning, Feature Recognition, Phases of Process planning. Knowledge Based System for Equipment Selection (KBSES) - Manufacturing system design. Equipment Selection Problem, Modeling the Manufacturing Equipment Selection Problem, Problem Solving approach in KBSES, Structure of the KBSES.

UNIT-V

GROUP TECHNOLOGY: Models and Algorithms Visual Method, Coding Method, Cluster Analysis Method, Matrix Formation - Similarity Coefficient Method, Sorting-based Algorithms, Bond Energy

Algorithm, Cost Based method, Cluster Identification Method, Extended CI Method. Knowledge Based Group Technology - Group Technology in Automated Manufacturing System. Structure of Knowledge based system for group technology (KBSCIT) — Data Base, Knowledge Base, Clustering Algorithm.

TEXT BOOKS:

1. Intelligent Manufacturing Systems/ Andrew Kusiak/Prentice Hall.
2. Artificial Neural Networks/ Yagna Narayana/PHI/2006
3. Automation, Production Systems and CIM / Groover M.P./PHI/2007

I – II	L	P	Credits
	-	6	2
(ELECTIVE IV)			
INTELLIGENT MANUFACTURING SYSTEMS			

MODELING AND ANALYSIS OF MANUFACTURING PROCESSES LAB

Students shall carry out the modeling and FE analysis of at least three processes of each category given below.

1. Casting processes - Simulation of Solidification, temperatures, Residual stresses, metallurgical phases etc.
2. Forging processes - Simulation of cold working and hot working processes for extrusion, drawing, rolling, etc.
3. Forming Processes – Simulation of blanking, bending, deep drawing, etc.
4. Welding Processes – Simulation of arc, spot, laser welding, etc